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### Notification Details

#### Description of Change:

Texas Instruments Incorporated is announcing an information only notification.

The product datasheet(s) is being updated as summarized below.

The following change history provides further details.



**TPS65381-Q1**

SLVSBC4G – MAY 2012 – REVISED JUNE 2017

#### Changes from Revision F (May 2016) to Revision G

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• Added the condition of VBATP = VBAT_SAFING to 6.1, 6.2, 6.3, 6.4, 6.5, 6.8, 6.9, 6.10, 6.11, 6.12, 6.13, 6.14, 6.15, 6.16, 6.17 in the <i>ELECTRICAL CHARACTERISTICS</i> table. ....	<a href="#">34</a>
• Added the condition of VBATP = VBAT_SAFING = 12 V to 7.1, 7.2, 7.3, 7.4, 7.7 and 7.8 the <i>ELECTRICAL CHARACTERISTICS</i> table.....	<a href="#">35</a>
• Changed test condition for the I <sub>IGN</sub> parameter (7.4) to 36 V, added clarification that VBATP = VBAT_SAFING = 36 V in the <i>ELECTRICAL CHARACTERISTICS</i> table .....	<a href="#">35</a>
• Changed test condition for the I <sub>CANWU</sub> parameter (7.7) to 36 V, added clarification that VBATP = VBAT_SAFING = 36 V in the <i>ELECTRICAL CHARACTERISTICS</i> table .....	<a href="#">35</a>
• Added clarification for C <sub>pump</sub> and C <sub>store</sub> connections in the <i>Charge Pump</i> section of the <i>ELECTRICAL CHARACTERISTICS</i> table.....	<a href="#">35</a>
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• Added clarification in statement for the <i>Timing Requirements</i> table by adding VBAT_SAFING recommended operating range in addition to VBATP recommended operating range .....	<a href="#">36</a>

(1) The recommended maximum operating voltage for VBATP and VBAT\_SAFING is listed as 34 V, just below the overvoltage detection thresholds for VBATP, VBATP\_OV<sub>rise</sub> and VBATP\_OV<sub>fall</sub>. TI recommends enabling overvoltage detection on VBATP (default is enabled, MASK\_VBATP\_OV = 0). TI also recommends evaluating the thermal and power dissipation of the device in the application and ensure the design has adequate thermal management for operation at the necessary supply voltage level.

- Changed description of parameter from Test Condition column to a footnote on the parameter in the *Timing Requirements* table for parameters 6.7, 11.1 ..... [36](#)
- Changed to clarify IGNITION and CAN WAKE-UP parameters (7.6 and 7.9) in *TIMING REQUIREMENTS* table.... [36](#)
- Added clarification in statement for the *Switching Characteristics* table by adding VBAT\_SAFING recommended operating range in addition to VBATP recommended operating range ..... [37](#)
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- Changed pin name to VTRACK1 for pin determining tracking or non-tracking mode in *VSOUT1 Linear Regulator* section describing what occurs after completion of the VDDx ramp-up ..... [42](#)
- Added note in the *Wake-Up* section on how to wake up the device for systems that need to power up and down with the power supply and do not need IGN or CANWU..... [44](#)
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- Changed to clarify LBIST functionality in the *Logic Built-In Self-Test (LBIST)* section..... [53](#)
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The datasheet number will be changing.

Device Family	Change From:	Change To:
TPS65381-Q1	SLVSBC4E	<b>SLVSBC4G</b>

<p>These changes may be reviewed at the datasheet links provided.  <a href="http://www.ti.com/product/TPS65381-Q1">http://www.ti.com/product/TPS65381-Q1</a></p>			
<b>Reason for Change:</b>			
To accurately represent the device characteristics.			
<b>Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):</b>			
No anticipated impact. This is a specification change announcement only.			
<b>Changes to product identification resulting from this PCN:</b>			
None.			
<b>Product Affected:</b>			
TPS65381QDAPRQ1			

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